

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in ITO220 internally insulated plastic package intended for use in applications requiring high thermal cycling performance and high junction temperature capability ($T_{j(max)} = 150\text{ °C}$).

2. Features and benefits

- High junction operating temperature capability ($T_{j(max)} = 150\text{ °C}$)
- High thermal cycling performance
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Internally insulated package
- Isolated mounting base with 2500 V (RMS) isolation

3. Applications

- Protection circuit in Power Supplies for Consumer / Industrial / Medical Equipment
- Ignition circuits
- Motor control
- Protection circuits e.g. SMPS inrush current
- Voltage regulation

4. Quick reference data

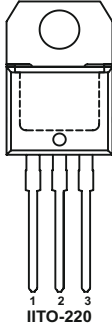

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute maximum rating				
V_{DRM}	repetitive peak off-state voltage		600	V
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 117\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	16	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	190	A
		half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$	209	A
T_j	junction temperature		150	°C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7	-	-	15	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9	-	-	40	mA
V_T	on-state voltage	$I_T = 16\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10	-	1.2	1.6	V
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}$; $T_j = 150\text{ °C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/ μ s

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
TYN16Y-600CT	IITO220	TYN16Y-600CTQ	Tube	50	IITO220E	15-Dec-2017

7. Marking

Table 4. Marking codes

Type number	Marking codes
TYN16Y-600CT	TYN16Y 600CT

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		600	V
V_{RRM}	repetitive peak reverse voltage		600	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 117\text{ °C}$	10.2	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 117\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	16	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	190	A
		half sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$	209	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine wave	180.5	A^2s
di_T/dt	rate of rise of on-state current	$I_G = 30\text{ mA}$	150	$A/\mu s$
I_{GM}	peak gate current		4	A
V_{RGM}	peak reverse gate voltage		5	V
P_{GM}	peak gate power		10	W
$P_{G(AV)}$	average gate power	over any 20 ms period	1	W
T_{stg}	storage temperature		-40 to 150	$^{\circ}C$
T_j	junction temperature		150	$^{\circ}C$

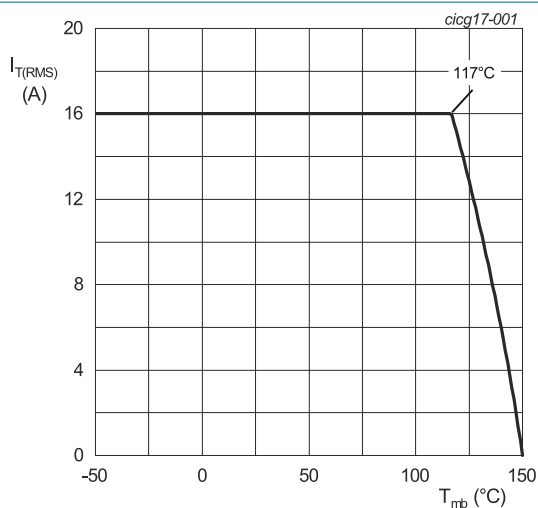


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

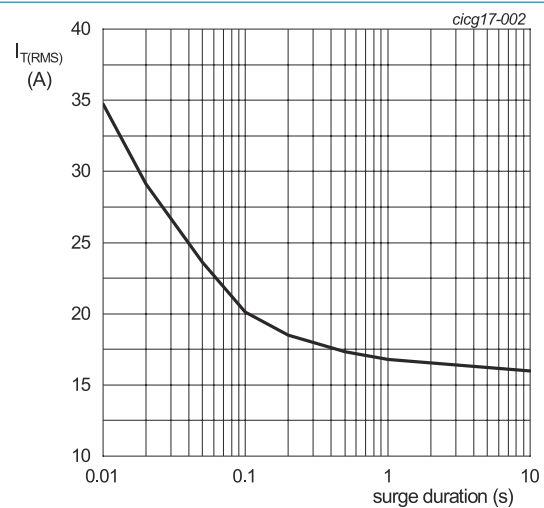
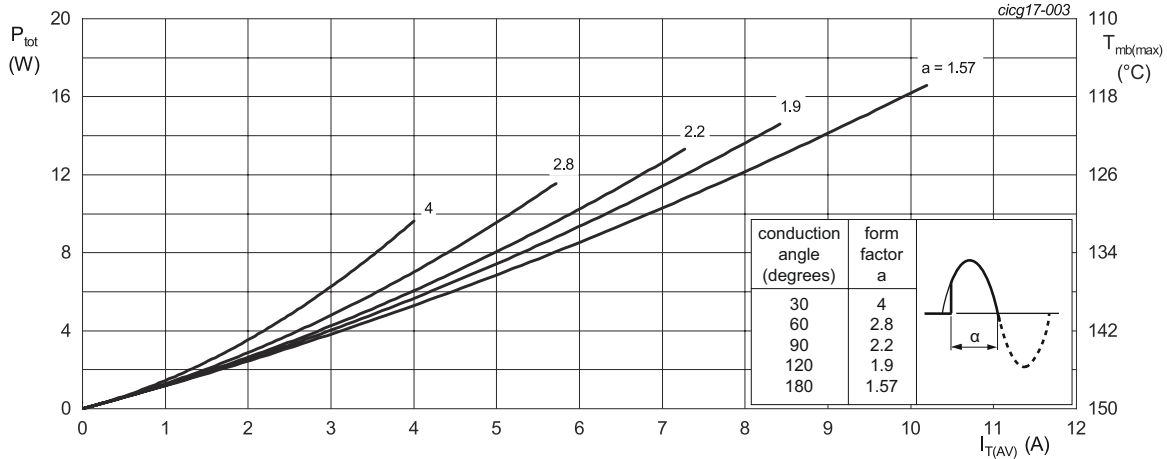
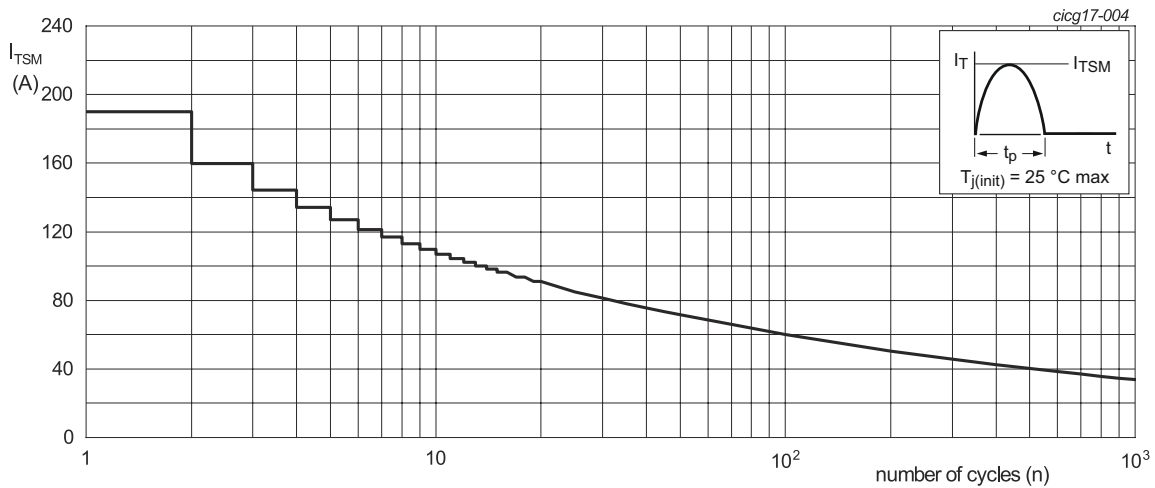


Fig. 2. RMS on-state current as a function of surge duration; maximum values
 $f = 50\text{ Hz}$; $T_{mb} = 117\text{ °C}$



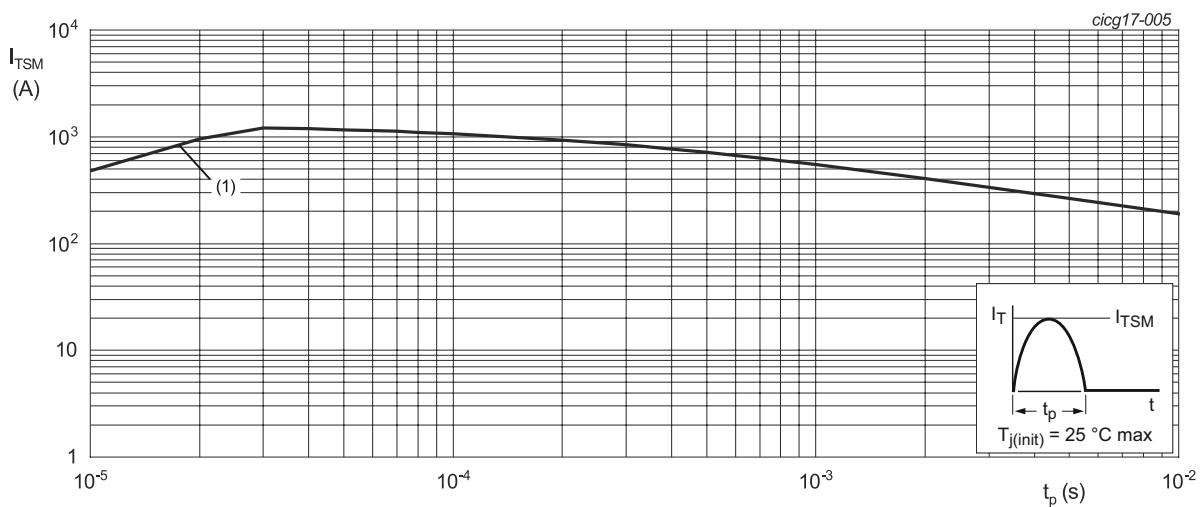
α = conduction angle
 a = form factor = $I_{T(RMS)} / I_{T(AV)}$

Fig. 3. Total power dissipation as a function of average on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 10$ ms ;
 (1) di_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6	-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

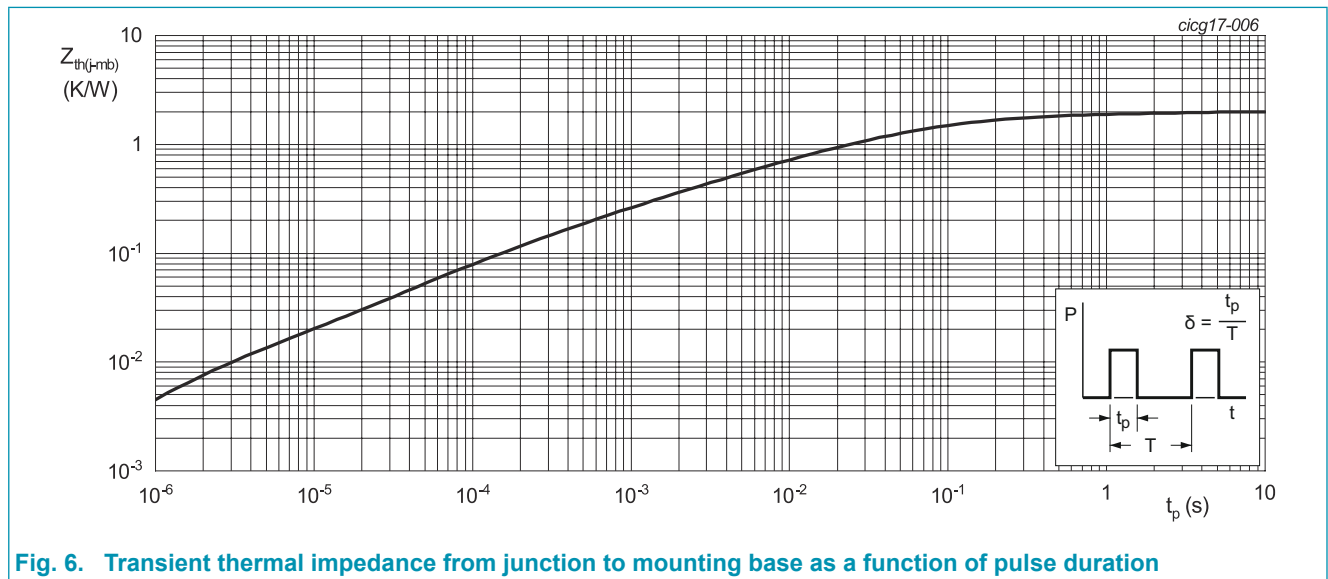


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Isolation characteristics

Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz \leq f \leq 60 Hz; RH \leq 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C_{isol}	isolation capacitance	from cathode to external heatsink	-	10	-	pF

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7	-	-	15	mA
I_L	latching current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 8	-	-	60	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9	-	-	40	mA
V_T	on-state voltage	$I_T = 16\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10	-	1.2	1.6	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 11	-	0.7	1	V
		$V_D = 400\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 150\text{ °C}$	0.2	0.4	-	V
I_D	off-state current	$V_D = 600\text{ V}$; $T_j = 150\text{ °C}$	-	-	1	mA
I_R	reverse current	$V_D = 600\text{ V}$; $T_j = 150\text{ °C}$	-	-	1	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}$; $T_j = 150\text{ °C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/ μ s
t_{gt}	gate-controlled turn-on time	$I_{TM} = 16\text{ A}$; $V_D = 600\text{ V}$; $I_G = 100\text{ mA}$; $(dI_G/dt)_M = 5\text{ A}/\mu\text{s}$; $T_j = 25\text{ °C}$	-	2	-	μ s
t_q	commutated turn-off time	$V_{DM} = 402\text{ V}$; $T_j = 150\text{ °C}$; $I_{TM} = 16\text{ A}$; $V_R = 25\text{ V}$; $dV_D/dt = 50\text{ V}/\mu\text{s}$; $(dI_T/dt)_M = 30\text{ A}/\mu\text{s}$; $R_{GK(ext)} = 100\ \Omega$; ($V_{DM} = 67\%$ of V_{DRM})	-	70	-	μ s

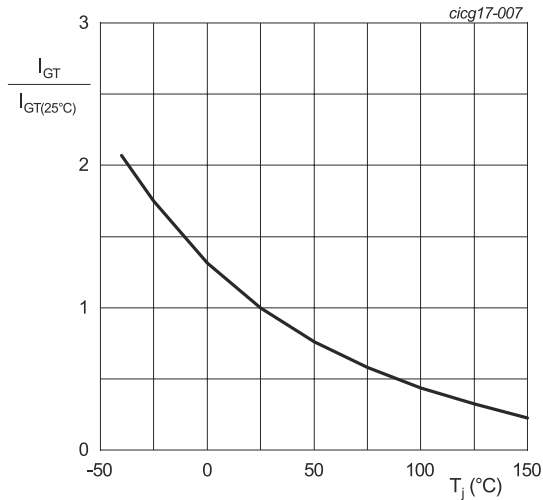


Fig. 7. Normalized gate trigger current as a function of junction temperature

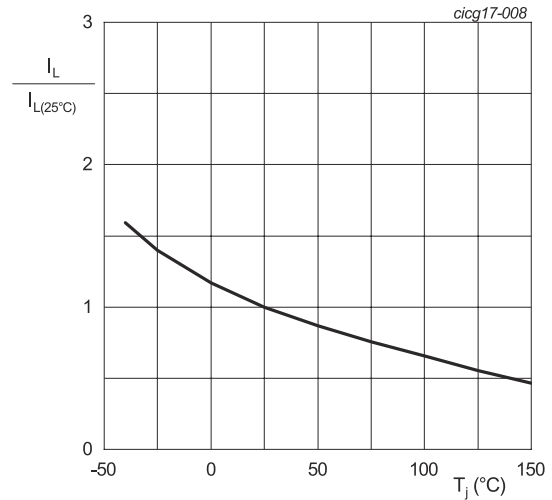


Fig. 8. Normalized latching current as a function of junction temperature

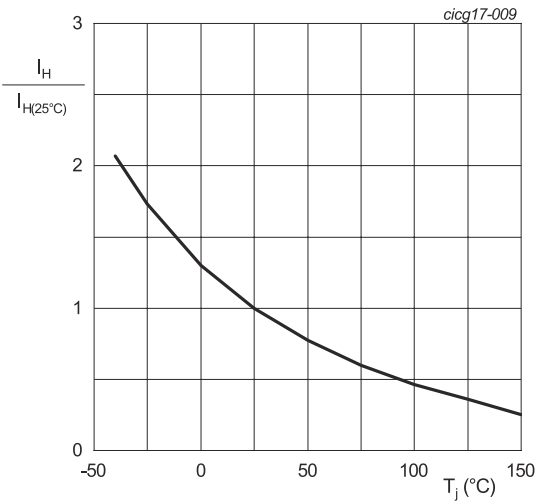
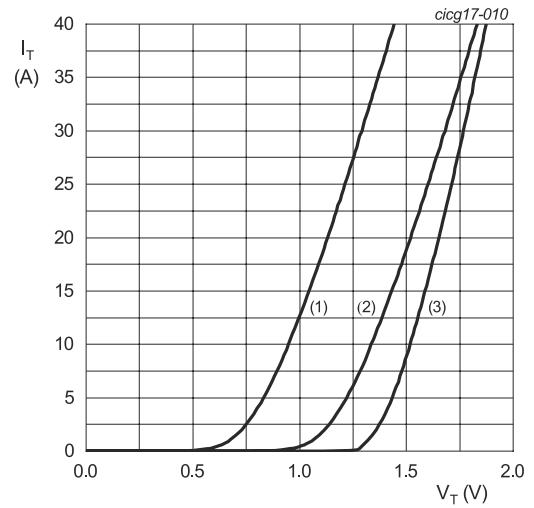


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.126 \text{ V}; R_s = 0.0200 \ \Omega$
 (1) $T_j = 150 \text{ }^\circ\text{C}$; typical values
 (2) $T_j = 150 \text{ }^\circ\text{C}$; maximum values
 (3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

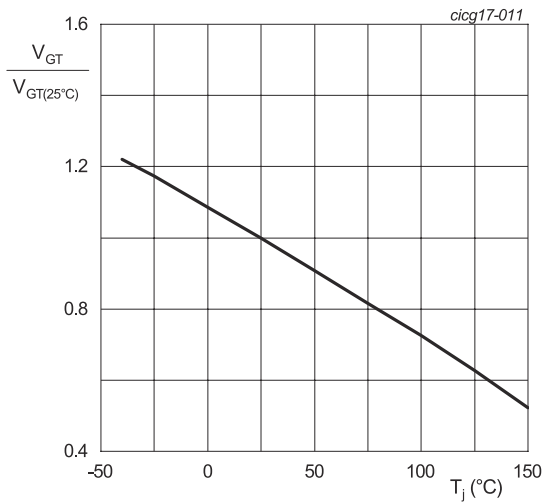
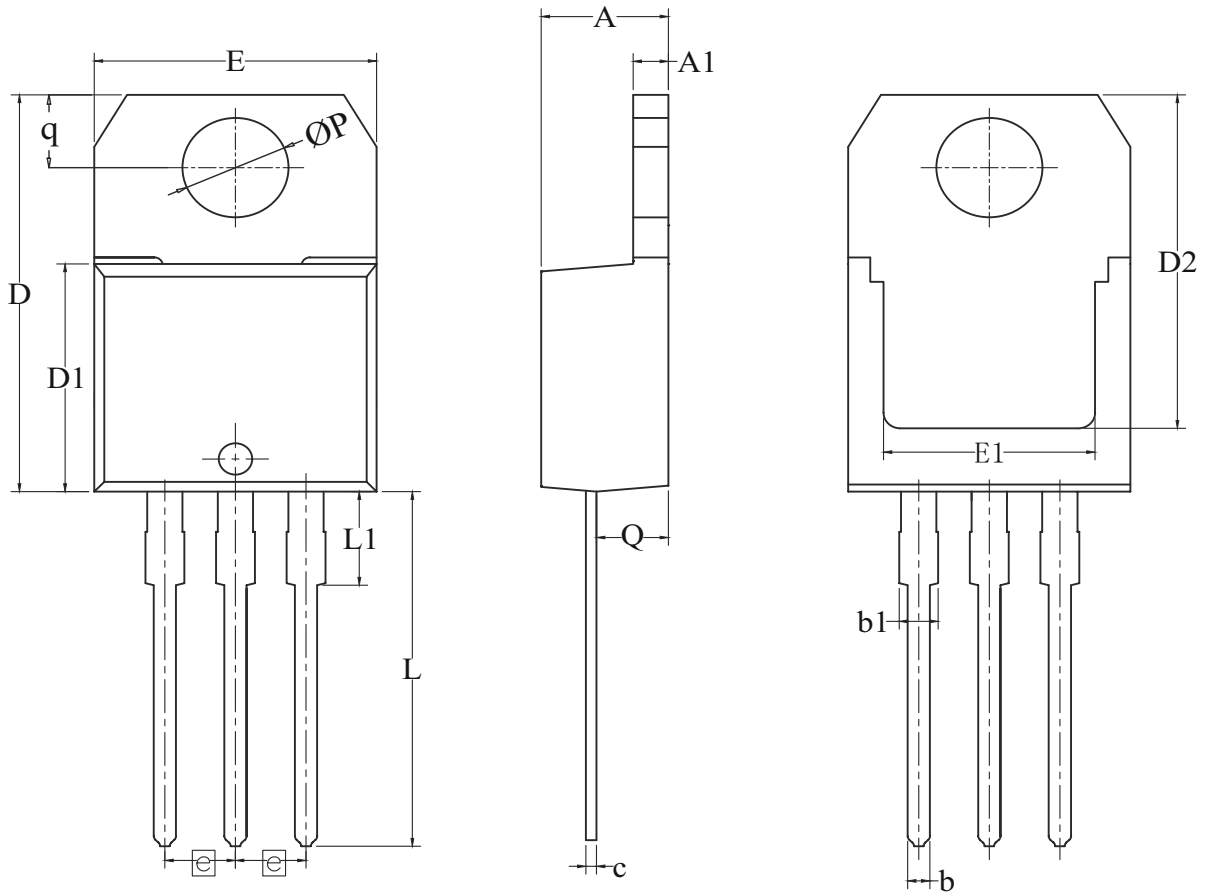


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 leads TO-220

IITO220



Unit	A	A1	b	b1	c	D	D1	D2	E	E1	e	L	L1	P	Q	q
MM	min	4.30	1.25	0.69	1.20	0.40	15.20	8.50	12.20	10.00	6.86	12.80	2.70	3.70	2.40	2.70
	max	4.70	1.40	0.90	1.72	0.60	16.00	9.02	12.88	10.40	8.89	14.00	3.30	3.95	2.80	3.00

13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Date of release: 11 June 2020
